



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7BD1*088VBM1	A	3068	2017-11-30
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	Package: D2PAK CLIP. MDF valid for CPs: T850-8G-TR and T850-8G			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.14	Die	99
Lead	4.84	Soft solder	3508
Lead-Borate Glass	0.44	Die	320

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	7BD1*088VBM1					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.706	mg	supplier	die	Silicon (Si)	7440-21-3		5.033	mg	882054	3647
				supplier	metallization	Gold (Au)	7440-57-5		0.019	mg	3330	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.029	mg	5082	21
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1052	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.137	mg	24010	99
				supplier	glass coating	Glass : Aluminium Oxide (Al2O3)	1344-28-1		0.041	mg	7185	30
Leadframe	Copper & its alloys	900.740	mg	JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.441	mg	77287	320
				supplier	alloy	Copper (Cu)	7440-50-8		899.839	mg	999000	652057
Soft solder	Solder	5.260	mg	JIG - R	solder	CopperPhosphorous (CuP)	12517-41-8		0.901	mg	1000	653
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.841	mg	920342	3508
				supplier	solder	Silver (Ag)	7440-22-4		0.131	mg	24905	95
				supplier	solder	Tin (Sn)	7440-31-5		0.262	mg	49810	190
				supplier	solder	flux residue	Proprietary		0.026	mg	4943	19
Encapsulation	Other Organic Materials	430.355	mg	supplier	mold compound	Silica, vitreous	60676-86-0		327.070	mg	760000	237007
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		43.896	mg	102000	31809
				supplier	mold compound	Phenol resin	9003-35-4		25.821	mg	60000	18711
				supplier	mold compound	Others	Proprietary		21.518	mg	50001	15593
				supplier	mold compound	Metal hydroxide	21645-51-2		8.607	mg	20000	6237
				supplier	mold compound	Carbon black	1333-86-4		3.443	mg	8000	2937
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
Clip	Copper & its alloys	31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917